HEWLETT-PACKARD COMPANY

Intellectual Property Administra P. O. Box 272400 Fort Collins, Colorado 80527-2400 72.05.07

PATENT APPLICATION

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FEE VALUE

ACCOUNTABILITY
DEPOSIT ACCOUNT NO

COPPOSED

ATTORNEY DOCKET NO. 10006165 -

IN THE U.S. PATENT AND TRADEMARK OFFICE Patent Application Transmittal Letter

COMMISSIO	VER FO	DR PA	TENTS
Washington,	D.C.	2023	31

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Transmitted herewith for filing under 37 CFR 1.53(b) is a(n):(X) Utility () Design

(X) original patent application,

() continuation-in-part applica

INVENTOR(S): Peter G. Hartwell et al

TITLE:

Methods For Dicing Wafer Stacks To Provide Access To Interior Structu

Enclosed are:

(X) The Declaration and Power of Attorney. (X) signed () unsigned or partial

(X) 8 sheets of drawings (one set) () Associate Power

() Form PTO-1449 ()

() Information Disclosure Statement and Form PTO-1449

() Priority document(s) () (Other) (fee \$

	CLAIMS A	AS FIL	ED BY OTHER T	HAN A SMALL I	ENTITY	_	
(1) FOR	(2) NUMBER FILED		1 (5)	(4) RATE		(5) TOTALS	
TOTAL CLAIMS	20 —	20	О	X \$18	\$	0	
INDEPENDENT CLAIMS	з —	3	0	X \$84	\$	0	
ANY MULTIPLE DEPENDENT CLAIMS	0			\$280	\$	0	
BASIC FEE: Design (\$330.00); Utility (\$740.00)				lity (\$740.00)	\$	740	
TOTAL FILING FEE				\$	740		
OTHER FEES				\$			
TOTAL CHARGES TO DEPOSIT ACCOUNT			\$	740			

Charge \$ 740 to Deposit Account 08-2025. At any time during the pendency of this application, please charge any fees required or credit any over payment to Deposit Account 08-2025 pursuant to 37 CFR 1.25. Additionally please charge any fees to Deposit Account 08-2025 under 37 CFR 1.16 through 1.21 inclusive, and any other sections in Title 37 of the Code of Federal Regulations that may regulate fees. A duplicate copy of this sheet is enclosed.

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I hereby certify that this is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and is addressed to: Commissioner for Patents, Washington, D.C. 20231.

By Chai Huyxun

Typed Name: Chris Grifin

Respectfully submitted,

Peter G. Hartwell et.a

William H. MacAllister

Attorney/Agent for Applicant(s)

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PATENT APPLICATION DOCKET NO. 10006165-1

Methods For Dicing Wafer Stacks To Provide

Access To Interior Structures

INVENTOR(S):

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